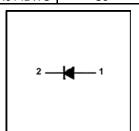


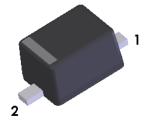
March 2008

# 1N4148WS / 1N4448WS / 1N914BWS Small Signal Diodes Device Marking Code

- · General Purpose Diodes
- Fast switching Device( TRR < 4.0 ns )
- Very Small and Thin SMD package
- Moisture Level Sensitivity 1
- Pb-free Version and RoHS Compliant
- Matte Tin (Sn) Lead Finish
- Green Mold Compound

Device Marking Code			
Device Type	Device Marking		
1N4148WS	S1		
1N4448WS	S2		
1N914BWS	S3		





\*Band Denotes Cathode SOD-323F

# Absolute Maximum Ratings\* T<sub>a</sub>=25°C unless otherwise noted

Symbol	Parameter	Value	Units	
V <sub>RSM</sub>	Non-Repetitive Peak Reverse Voltage	100	V	
V <sub>RRM</sub>	Repetitive Peak Reverse Voltage	75	V	
I FRM	Repetitive Peak Forward Current	300	mA	
Io	Continuous Forward Current	150	mA	
T <sub>J</sub>	Operating Junction Temperature Range	+150	°C	
T <sub>STG</sub>	Storage Temperature Range -55 to +19		°C	

<sup>\*</sup> These ratings are limiting values above which the serviceability of any semiconductor device may be impaired. The factory should be consulted on applications involving pulsed or low duty cycle operations.

## **Thermal Characteristics**

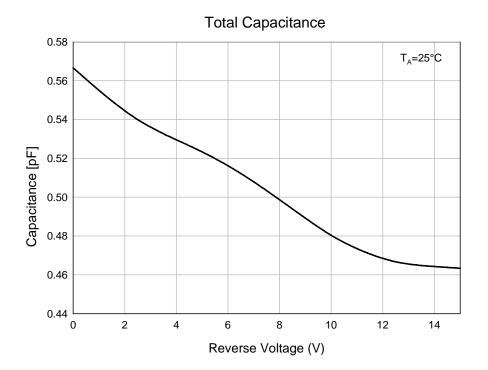
Symbol	Parameter	Value	Unit
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	500	°C/W
$P_{D}$	Power Dissipation(T <sub>C</sub> =25°C) 200		mW

<sup>\*</sup> Device mounted on FR-4 PCB minimum land pad.

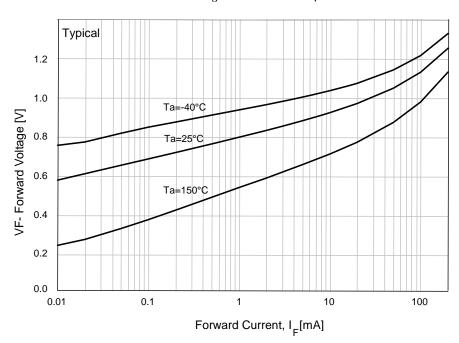
# Electrical Characteristics T<sub>a</sub>=25°C unless otherwise noted

Symbol	Parameter		Test Conditions	Min	Тур	Max	Units
BV <sub>R</sub>	Breakdown Voltage		I <sub>R</sub> = 100 μA I <sub>R</sub> = 5 μA	100 75			V
I <sub>R</sub>	Reverse Current		V <sub>R</sub> = 20 V V <sub>R</sub> = 75 V			25 5	nA μA
V <sub>F</sub>	Forward Voltage	1N4448WS/ 914BWS 1N4148WS 1N4448WS/ 914BWS	$I_F = 5 \text{ mA}$ $I_F = 10 \text{ mA}$ $I_F = 100 \text{ mA}$	0.62		0.72 1 1	V
Co	Diode Capacitance		V <sub>R</sub> = 0, f = 1 MHz			4	pF
T <sub>RR</sub>	Reverse Recovery Time		$I_F = 10 \text{ mA}, I_R = 60 \text{mA}$ $I_{RR} = 1 \text{ mA}, R_L = 100 \Omega$			4	nS

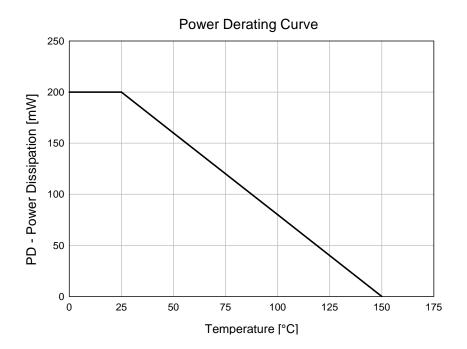
# **Typical Performance Characteristics**

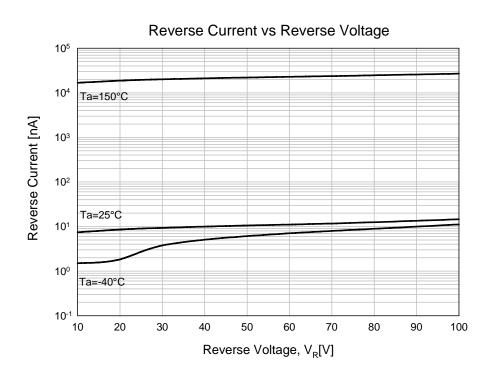


## Forward Voltage vs Ambient Temperature

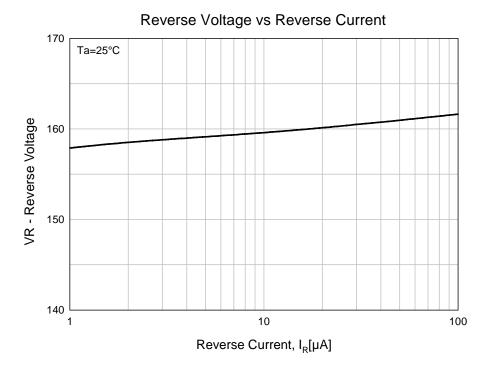


# **Typical Performance Characteristics**



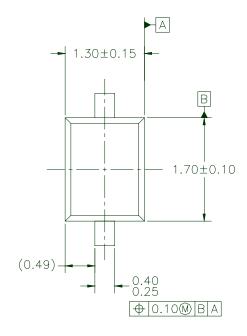


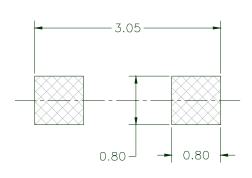
# **Typical Performance Characteristics**



# **Package Dimensions**

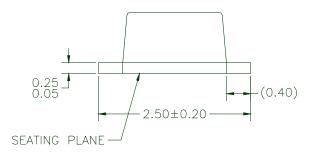
# **SOD-323F**





LAND PATTERN RECOMMENDATION





NOTES: UNLESS OTHERWISE SPECIFIED

- THIS PACKAGE IS COMPLIANT TO JEITA SC90 STANDARD EXCEPT FOR THE OVERALL PACKAGE HEIGHT.
- ALL DIMENSIONS ARE IN MILLIMETERS.
- DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH AND TIE BAR EXTRUSIONS. DIMENSIONING AND TOLERANCING PER ASME Y14.5M 1994.

MKT-SOD323F2REV1





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No Identification Needed	Full Production	This datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design.
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